PRODUCT / PROCESS CHANGE INFORMATION

| 1. PCI basic data | | |
|----------------------|--|--|
| 1.1 Company | | STMicroelectronics International N.V |
| 1.2 PCI No. | | EMBEDDED PROCESSING/25/15372 |
| 1.3 Title of PCI | | STM32H7Rxx and STM32H7Sxx - Product BootLoader & secure firmware enhancement |
| 1.4 Product Category | | STM32H7R3x, STM32H7R7x STM32H7S3x, STM32H7S7x |
| 1.5 Issue date | | 2025-10-23 |

| 2. PCI Team | | |
|---------------------------|---------------------|--|
| 2.1 Contact supplier | | |
| 2.1.1 Name | PIKE EMMA | |
| 2.1.2 Phone | +44 1628896111 | |
| 2.1.3 Email | emma.pike@st.com | |
| 2.2 Change responsibility | | |
| 2.2.1 Product Manager | Patrick AIDOUNE | |
| 2.1.2 Marketing Manager | Veronique BARLATIER | |
| 2.1.3 Quality Manager | Pascal NARCHE | |

| 3. Change | | | |
|--------------------------|---|----------------------------|--|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location | |
| General Product & Design | Firmware modification: firmware is programed in the memory without effect of electrical performance at the customer (bug fix) | ST Crolles (France) | |

| 4. Description of change | | |
|---|---|---|
| | Old | New |
| 4.1 Description | STM32H7Rx and STM32H7Sx (Die485 - cut2.0 revision B) System Flash Security Package (SFSP) has limitations | STM32H7Rx and STM32H7Sx (Die485 - cut2.0 revision B) System Flash Security Package (SFSP) enhancement. Change of security descriptor located on Bootloader area needed for integration w/ SFSP: - The change of the SFSP descriptor located in Bootloader area has no impact on Bootloader The Bootloader binary remains unchanged Changes done in SFSP descriptor: change the address in API table for RSS services. ES0596 device Errata sheet: New Rev. 7 (replacing Rev. 6). AN6022 SFSP Application Note: New SFSP version v2.1.0 (replacing the v2.0.0). AN2606 application Note: - New Revision 69 - 45 2025 (replacing Rev 68) New Bootloader version V14.5 (replacing V14.4). |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact, no datasheet change. | |

| 5. Reason / motivation for change | | |
|-----------------------------------|---------------------|--|
| 5.1 Motivation | Bug Fix | |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT | |

| 6. Marking of parts / traceability of change | |
|--|---|
| 6.1 Description | Traceability ensured by ST internal tools |

| 7. Timing / schedule | |
|--|------------|
| 7.1 Date of qualification results | 2025-10-08 |
| 7.2 Intended start of delivery | 2025-11-10 |
| 7.3 Qualification sample available? Not Applicable | |

| 8. Qualification / Validation | | | |
|---|----------------------------|---------------|------------|
| 8.1 Description 15372 Qualification document not applicable.pdf | | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2025-10-23 |

9. Attachments (additional documentations) 15372 Public product.pdf 15372 Qualification document not applicable.pdf

| 10. Affected parts | | | |
|-------------------------|-------------------------|--------------------------|--|
| 10. 1 Current | | 10.2 New (if applicable) | |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No | |
| | STM32H7R3A8I6 | | |
| | STM32H7R3I8K6 | | |
| | STM32H7R3I8T6 | | |
| | STM32H7R3L8H6 | | |
| | STM32H7R3L8H6H | | |
| | STM32H7R3V8T6 | | |
| | STM32H7R3V8Y6TR | | |
| | STM32H7R3Z8J6 | | |
| | STM32H7R3Z8T6 | | |
| | STM32H7R7A8I6 | | |
| | STM32H7R7I8K6 | | |
| | STM32H7R7I8T6 | | |
| | STM32H7R7L8H6 | | |
| | STM32H7R7L8H6H | | |
| | STM32H7R7Z8J6 | | |
| | STM32H7S3A8I6 | | |
| | STM32H7S3I8K6 | | |
| | STM32H7S3I8T6 | | |
| | STM32H7S3L8H6H | | |
| | STM32H7S3V8H6 | | |
| | STM32H7S3V8T6 | | |
| | STM32H7S3V8Y6TR | | |
| | STM32H7S3Z8J6 | | |
| | STM32H7S3Z8T6 | | |
| | STM32H7S7A8I6 | | |
| | STM32H7S7I8K6 | | |
| | STM32H7S7I8T6 | | |
| | STM32H7S7L8H6H | | |
| | STM32H7S7Z8J6 | | |
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